CLAIMS

1. A copper paste for joining, comprising: metal particles; and a dispersion medium, wherein

the copper paste for joining contains copper particles as the metal particles,

the copper paste for joining contains dihydroterpineol and a compound having a boiling point of 300°C or higher as the dispersion medium,

a content of the metal particles is 85 to 90% by mass on the basis of the total amount of the copper paste for joining,

a content of dispersion medium is 10 to 15% by mass on the basis of the total amount of the copper paste for joining,

a content of the dihydroterpineol is 60 to 80% by mass on the basis of the total amount of the dispersion medium,

a content of the compound having a boiling point of 300°C or higher is 20 to 40% by mass on the basis of the total amount of the dispersion medium, and

a viscosity at 25°C is 100 to 200 Pa·s.

2. The copper paste for joining according to claim 1, wherein a content of the copper particles is 80 to 100% by mass on the basis of the total mass of the metal particles.

3. The copper paste for joining according to claim 1 or 2, wherein the copper paste for joining is for screen printing.

4. The copper paste for joining according to any one of claims 1 to 3, wherein the copper paste for joining contains submicro copper particles having a volume average particle diameter of 0.12 to 0.8 μm and flake-

shaped micro copper particles having a maximum diameter of 2 to 50 μm and an aspect ratio of 3.0 or more as the copper particles.

5. The copper paste for joining according to claim 4, wherein a content of the submicro copper particles is 30 to 90% by mass on the basis of the total mass of the copper particles, and

a content of the micro copper particles is 10 to 70% by mass on the basis of the total mass of the copper particles.

6. The copper paste for joining according to any one of claims 1 to 5, wherein the copper paste for joining is for non-pressurization joining.

7. A method for manufacturing a joined body which includes a first member, a second member, and a joining portion that joins the first member and the second member, the method comprising:

a first step of printing the copper paste for joining according to claim 1, 2, 4, or 5 to at least one joining surface of the first member and the second member to prepare a laminate having a laminate structure in which the first member, the copper paste for joining, and the second member are laminated in this order; and

a second step of sintering the copper paste for joining of the laminate.

8. The method for manufacturing a joined body according to claim 7, wherein the printing is screen printing.

9. The method for manufacturing a joined body according to claim 7 or 8, wherein in the second step, the copper paste for joining is sintered by being heated under non-pressurization.

10. The method for manufacturing a joined body according to any one of claims 7 to 9, wherein at least one of the first member and the

second member is a semiconductor element.